

WHAT IS CLAIMED IS:

1. A method of manufacturing a circuit device, in which an IC and a passive part are covered with and supported by an insulating resin, using a terminal and a server which are connected to each other via a communication network, the method comprising:

a condition inputting step for inputting conditions to be satisfied by the circuit device through the terminal and transmitting the conditions from the terminal to the server;

a manufacturing data generating step for receiving the input conditions and generating, at the server side, manufacturing data for manufacturing the circuit device based on the conditions; and

a manufacturing step for manufacturing the circuit device based on the generated manufacturing data.

2. A method according to claim 1, further comprising:

an evaluating step for evaluating, at the server side, reliability of a circuit device to be manufactured based on the conditions when the conditions are received by the server and transmitting an evaluation result to the terminal.

3. A method according to claim 1, wherein

the conditions include at least an external size, a terminal size, a circuit diagram, IC specification data, and passive part specification data of the circuit device, and

in the manufacturing data generating step, a pattern design processing and a mask design processing are performed based on the conditions for generating, as the manufacturing data, at least mask data, parts placement data, and wire bonding coordinate data.

4. A method according to claim 1, wherein
in the condition inputting step, the conditions are input through a web page which is created by the server and
10 displayed on the terminal.

5. A method of manufacturing a circuit device, in which an IC and a passive part are covered with and supported by an insulating resin, using a terminal and a server which are
15 connected to each other via a communication network, the method comprising, at the server side, the steps of:

receiving conditions to be satisfied by the circuit device from the terminal;

generating manufacturing data for manufacturing the
20 circuit device based on the conditions; and

transmitting the generated manufacturing data to a circuit device manufacturing facility,

wherein the circuit device is manufactured using the manufacturing data in the circuit device manufacturing
25 facility.

6. A method according to claim 5, wherein

the conditions include at least an external size, a terminal size, a circuit diagram, IC specification data, and passive part specification data of the circuit device, and

the manufacturing data includes at least mask data, part
5 arrangement data, and wire bonding coordinate data.

7. A method according to claim 5, further comprising, at the server, the steps of:

evaluating reliability of a circuit device to be
10 manufactured based on the conditions; and

transmitting a reliability evaluation result to the terminal.